

ABSTRACT

A semiconductor package capable of spreading heat includes an upper PCB and a lower PCB connected to a first
5 chip and a second chip by using gold bumps, respectively. Also the semiconductor package includes a heat spreader and thermally conductive members. The heat spreader spreads the heat generated by the first chip and the second chip. The thermally conductive members transmit the heat to the heat
10 spreader by connecting the heat spreader to the first chip and the second chip with the thermally conductive members.

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